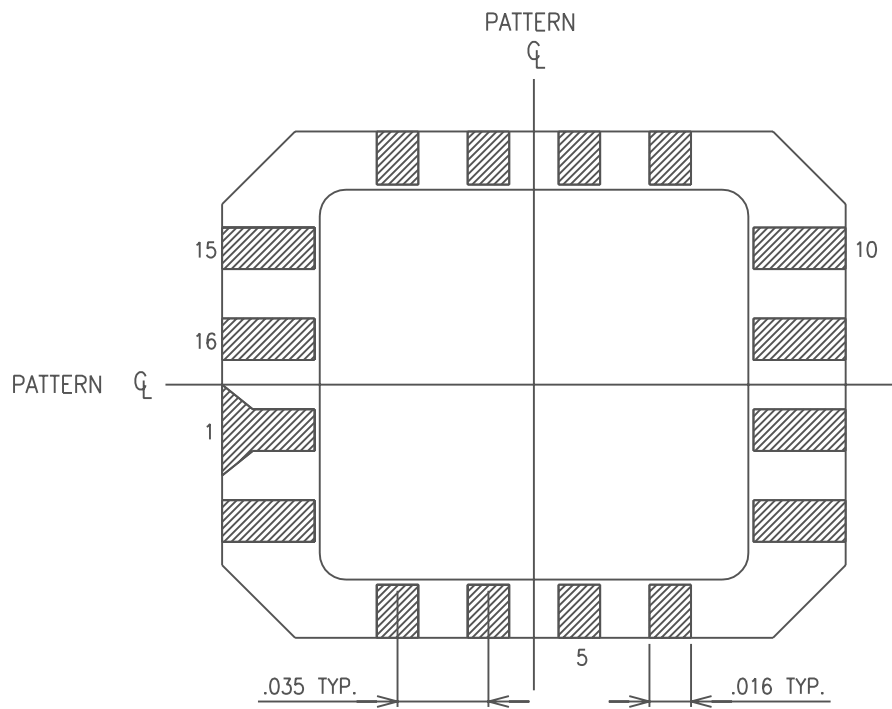


- NOTES:
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
  2. SEAL AREA TO BE METALLIZED.
  3. DIE ATTACH AREA TO BE METALLIZED.
  4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

MODIFICATION						NAME	16 LEAD FLAT PACKAGE				TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						SCALE	8/1				UNLESS OTHERWISE SPECIFIED	S.S	K.O		APR 29 '86
						MATERIAL	AS INDICATED				±.005				
	△ REDRAWN (CONVERTED CAD DATA)	ADDED: SHEET 2/2	01/27/91	K.I	H.S/S.F	T.A	KYOCERA CORPORATION KYOTO JAPAN				THIRD ANGLE PROJECTION	DRAWING NO.			SHEET
	CHANGED											KD-F86435-A			1/2





BONDING PATTERN

MODIFICATION						NAME	16 LEAD FLAT PACKAGE	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						SCALE	20/1	UNLESS OTHERWISE SPECIFIED	K.I	H.S/S.F	T.A	OCT.27.94
						MATERIAL		THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-F86435-A		SHEET	2/2

